

100mΩ Power Distribution Switches

General Description

The RT9701 is an integrated 100mΩ power switch for self-powered and bus-powered Universal Series Bus (USB) applications. A built-in charge pump is used to drive the N-channel NMOSFET that is free of parasitic body diode to eliminate any reversed current flow across the switch when it is powered off. Its low quiescent supply current (23μA) and small package (SOT-25) is particularly suitable in battery-powered portable equipment.

Several protection functions include soft start to limit inrush current during plug-in, current limiting at 1.5A to meet USB power requirement, and thermal shutdown to protect damage under over current conditions.

Applications

- Battery-Powered Equipment
- Motherboard USB Power Switch
- USB Device Power Switch
- Hot-Plug Power Supplies
- Battery-Charger Circuits

Ordering Information

RT9701-□ □□

- Package type
 - BL : SOT-25, w/o CE
 - B : SOT-25, with CE
 - X : SOT-89
- Operating temperature range
 - C: Commercial standard

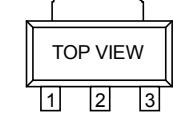
Marking Information

Part Number	Marking
RT9701-CBL	AH
RT9701-CB	C0
RT9701-CX	AR

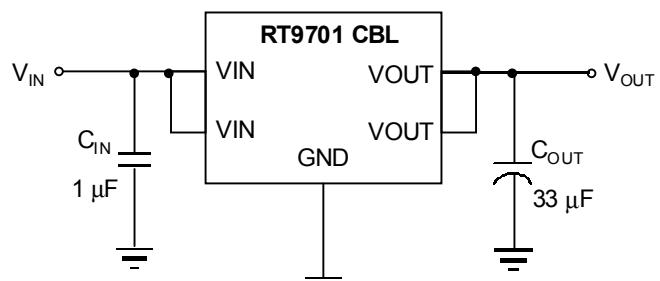
Features

- 100mΩ Typ. High-Side NMOSFET (SOT- 25)
- Guaranteed 1.1A Continuous Current
- 1.5A Current Limit
- Small SOT- 25 Package Minimizes Board Space
- Soft Start
- Thermal Protection
- Low 23μA Supply Current
- Wide Input Voltage Range: 2.2V ~ 6V

Pin Configurations

Part Number	Pin Configurations							
RT9701-CBL (SOT-25)	 <table> <tr> <td>5</td> <td>4</td> </tr> <tr> <td colspan="2">TOP VIEW</td> </tr> <tr> <td>1</td> <td>2</td> <td>3</td> </tr> </table>	5	4	TOP VIEW		1	2	3
5	4							
TOP VIEW								
1	2	3						
RT9701-CB (SOT-25)	 <table> <tr> <td>5</td> <td>4</td> </tr> <tr> <td colspan="2">TOP VIEW</td> </tr> <tr> <td>1</td> <td>2</td> <td>3</td> </tr> </table>	5	4	TOP VIEW		1	2	3
5	4							
TOP VIEW								
1	2	3						
RT9701-CX (SOT-89)	 <table> <tr> <td>TOP VIEW</td> </tr> <tr> <td>1</td> <td>2</td> <td>3</td> </tr> </table>	TOP VIEW	1	2	3			
TOP VIEW								
1	2	3						

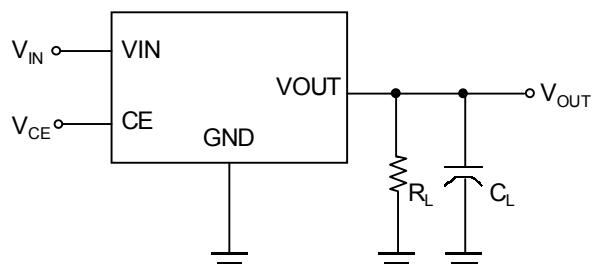
Typical Application Circuit



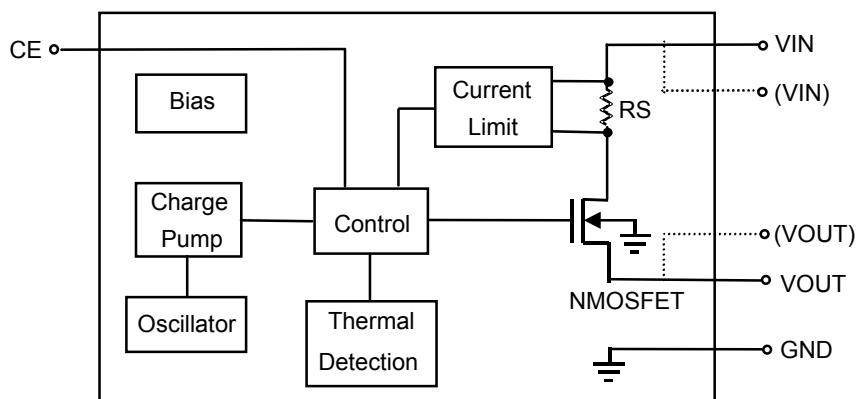
Pin Description

Pin Name	Pin Function
VIN	Input Pin
VOUT	Output Pin
GND	Power Ground Pin
CE	Chip Enable Control Pin

Test Circuit



Function Block Diagram



Absolute Maximum Ratings

• Supply Voltage V_{IN}	7V
• Chip Enable V_{CE}	-0.3V ~ 7V
• Power Dissipation	
SOT-25	0.25W
SOT-89	0.5W
• Operating Junction Temperature Range	-20°C ~ 100°C
• Storage Temperature Range	-65°C ~ 150°C
• Thermal Resistance	
SOT-25 θ_{JA}	250°C /W
SOT-89 θ_{JA}	100°C /W
• V_{OUT} EDS Level	
HBM (Human Body Mode)	8KV
MM (Machine Mode)	800V

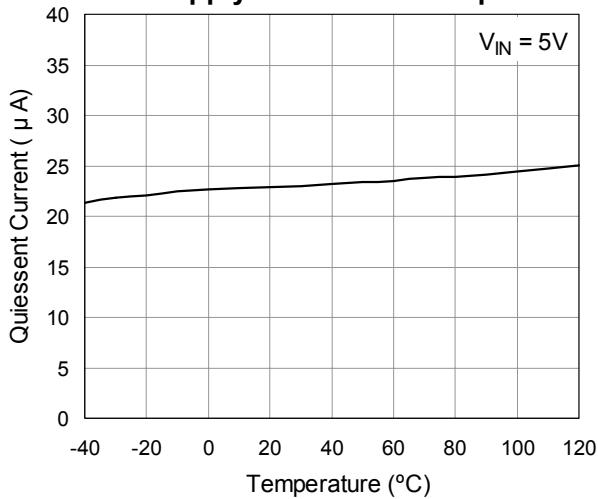
Electrical Characteristics

($V_{IN} = 5V$, $C_{IN} = C_{OUT} = 1\mu F$, $T_a = 25^\circ C$, unless otherwise specified)

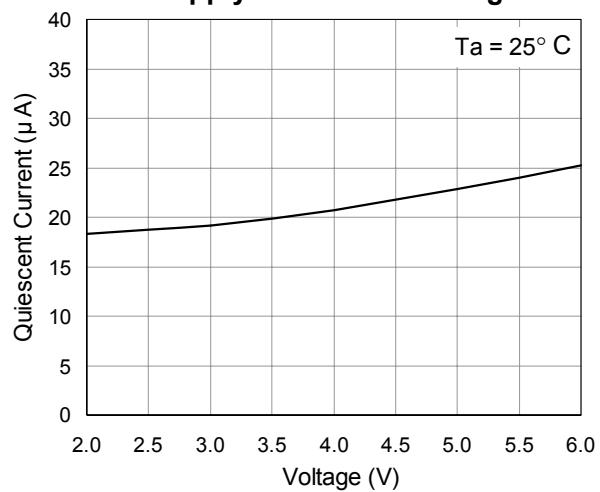
Parameter		Symbol	Test Conditions	Min	Typ	Max	Units
Input Voltage Range		V_{IN}		2.2		6	V
Output NMOFET $R_{DS(ON)}$	RT9701-CBL	$R_{DS(ON)}$	$I_L = 1A$		100	130	mΩ
	RT9701-CB		$I_L = 1A$		105	135	
	RT9701-CX		$I_L = 1A$		110	140	
Supply Current		I_{DD}	$V_{IN} = 3V$		19	40	μA
			$V_{IN} = 5V$		23	45	
Output Turn-On Rising Time		T_R	$R_L = 10\Omega$, 90% Settling		400		μS
Current Limit Threshold		I_{LIMIT}	$R_L = 2\Omega$	1.1	1.5	2	A
Short-circuit Output Current		I_{OS}	$V_{OUT} = 0V$		0.5		A
CE Input High Threshold	RT9701-CB	V_{CE}			2.0		V
CE Input Low Threshold	RT9701-CB					0.8	V
Shutdown Supply Current	RT9701-CBL	I_{OFF}	$CE = "0"$		0.1	1	μA
Output Leakage Current	RT9701-CBL		$CE = "0"$, $V_{OUT} = 0V$		0.5	10	μA
Under Voltage Lockout		$UVLO$		1.3	1.8		V
Under Voltage Hysteresis					100		mV
Thermal Limit					130		°C
Thermal Limit Hysteresis					20		°C

Typical Operating Characteristics

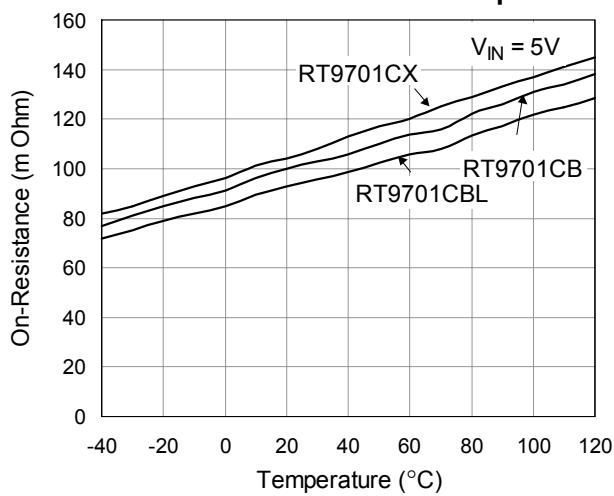
Supply Current vs. Temp.



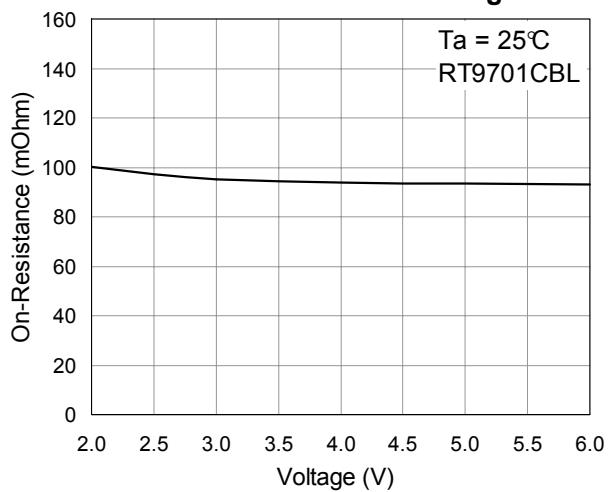
Supply Current vs. Voltage



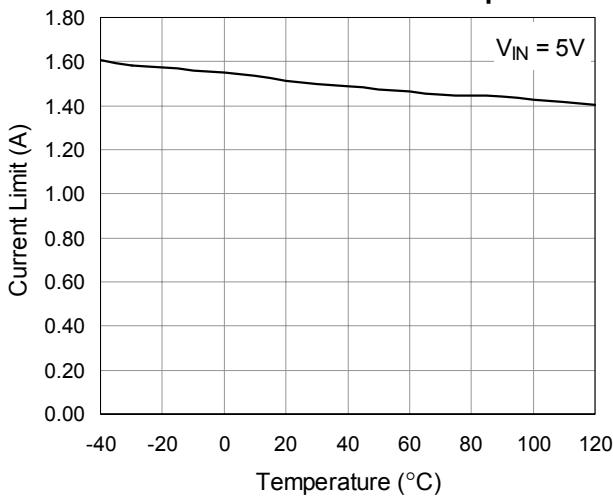
On-Resistance vs. Temp.



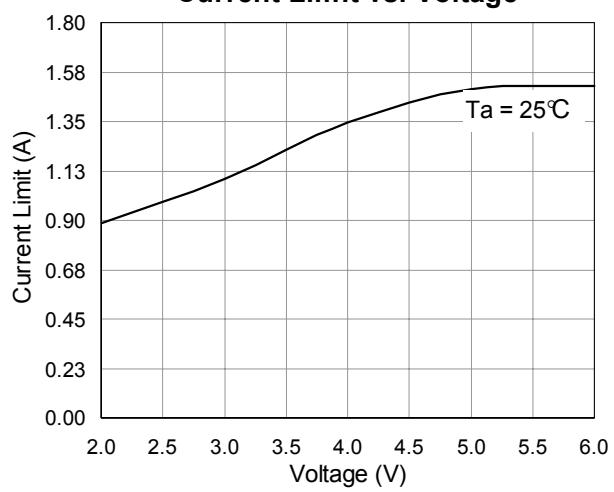
On-Resistance vs. Voltage

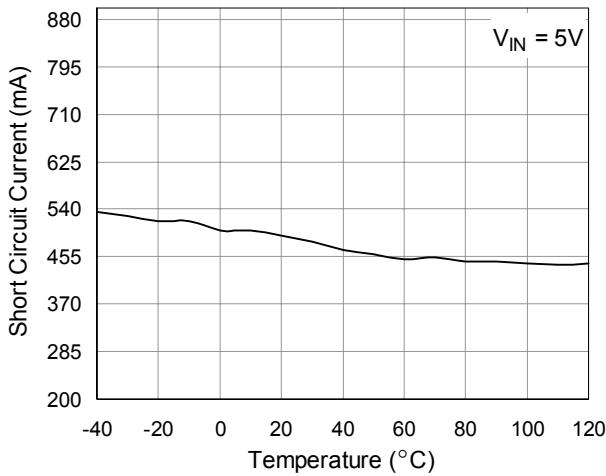
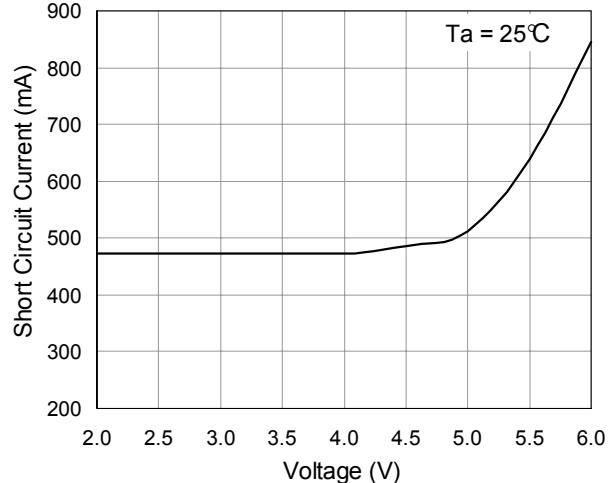
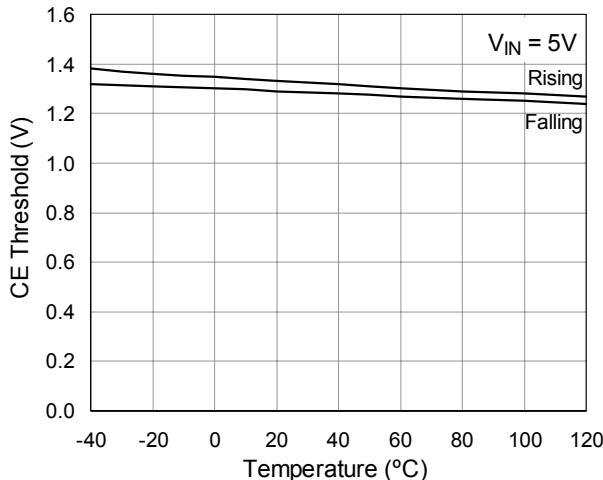
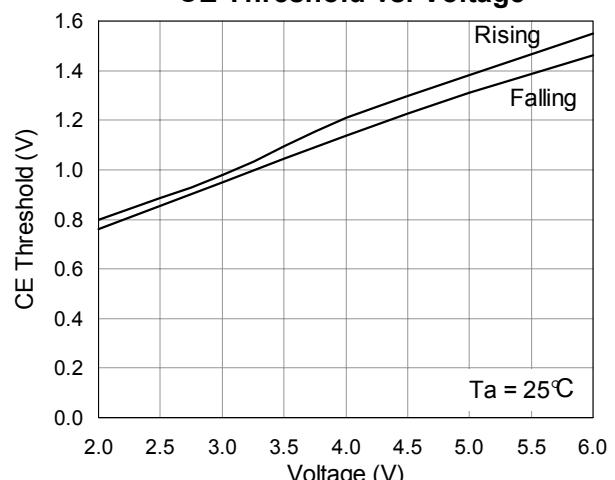
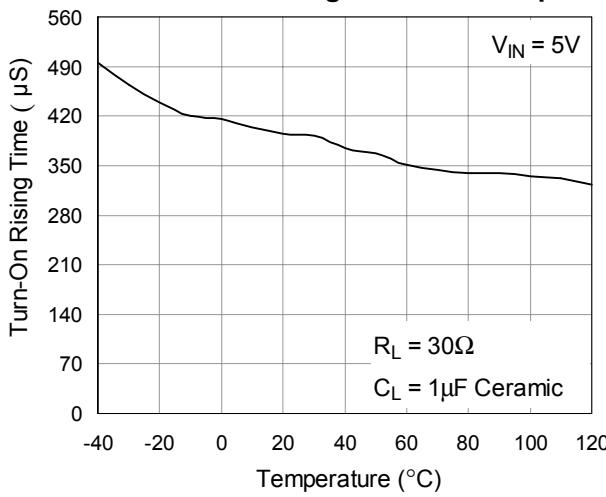
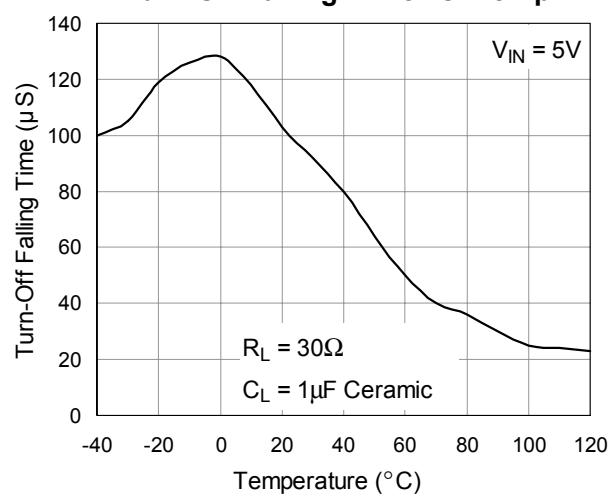


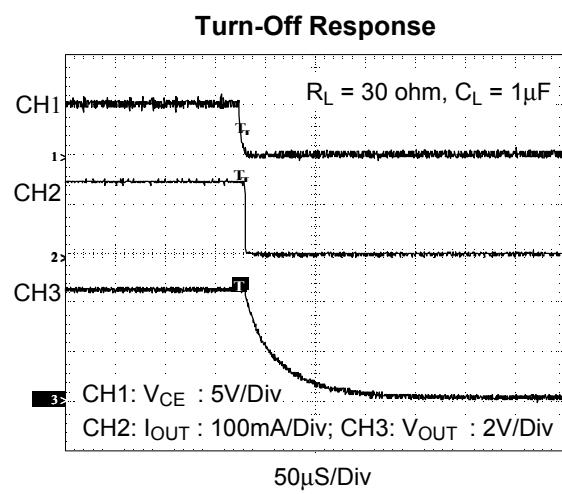
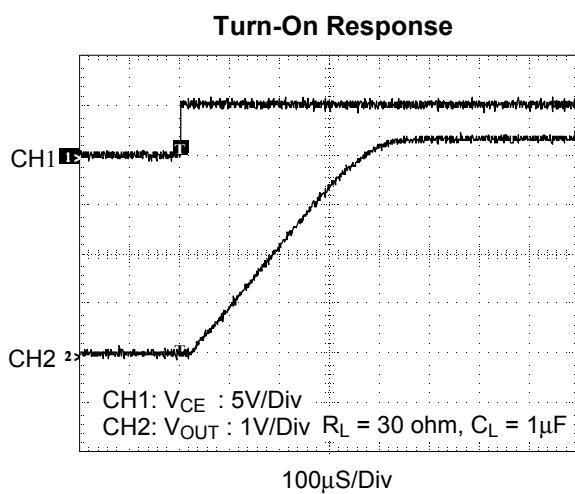
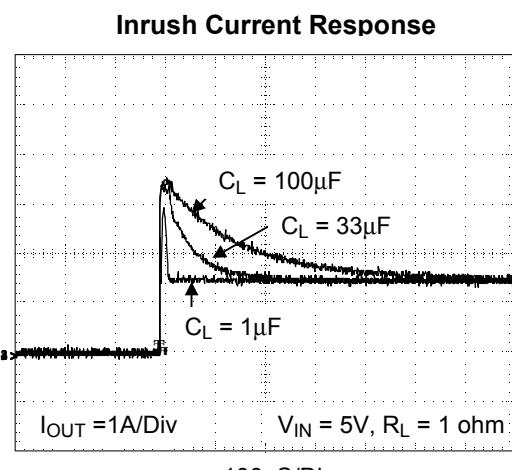
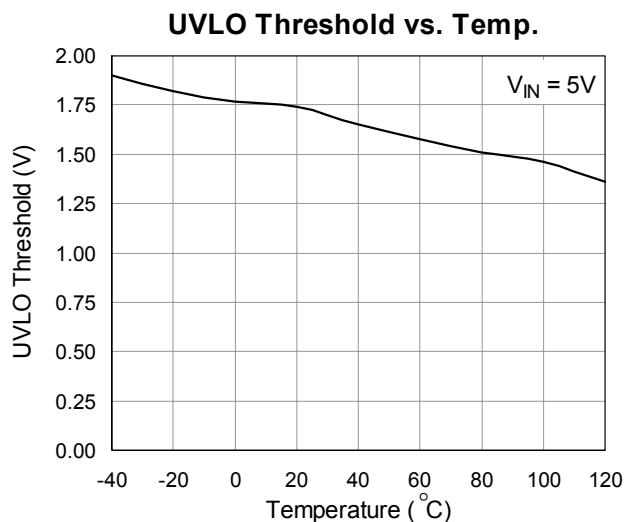
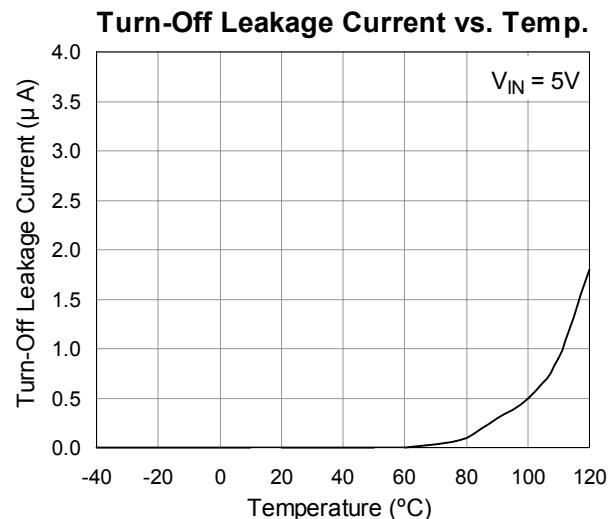
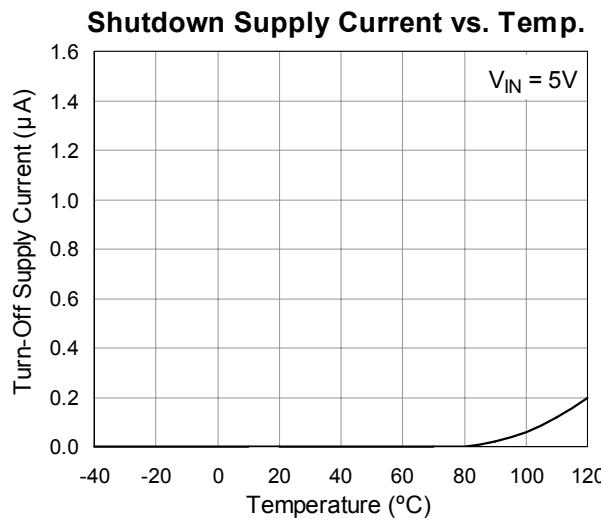
Current Limit vs. Temp.

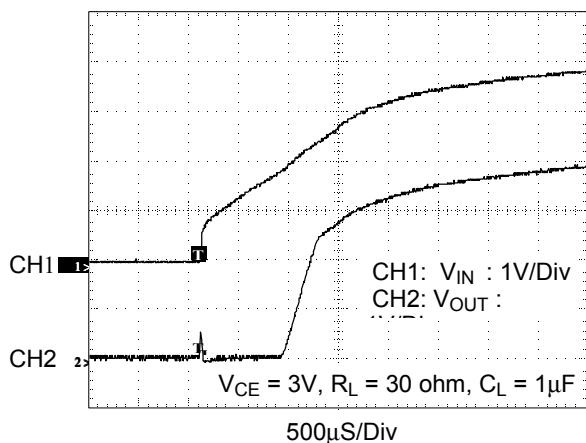
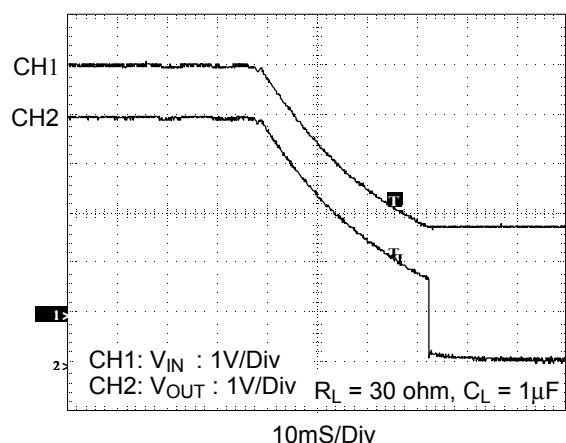
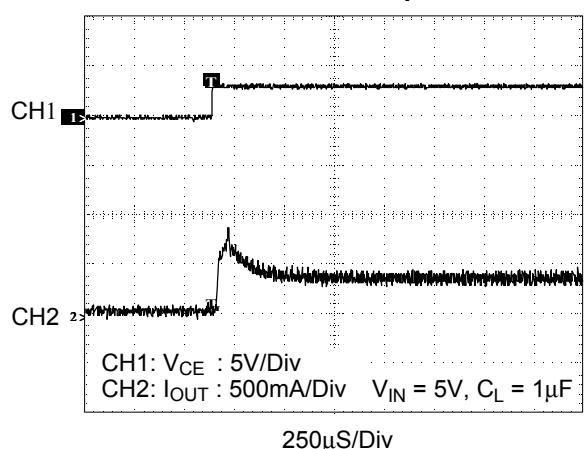
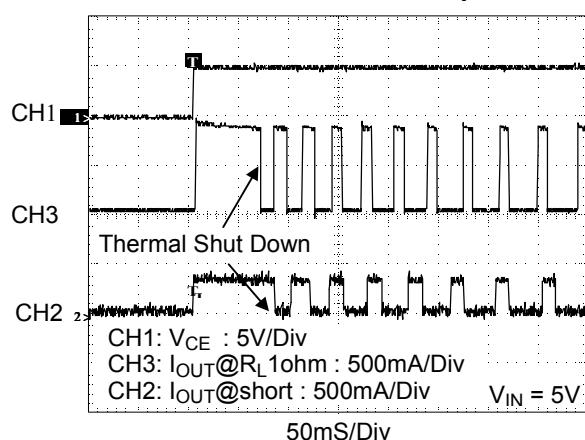
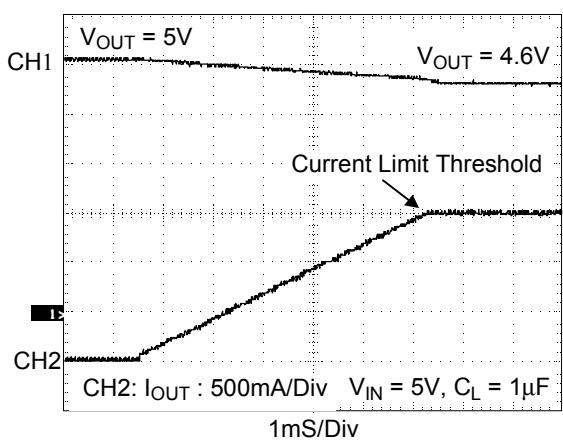
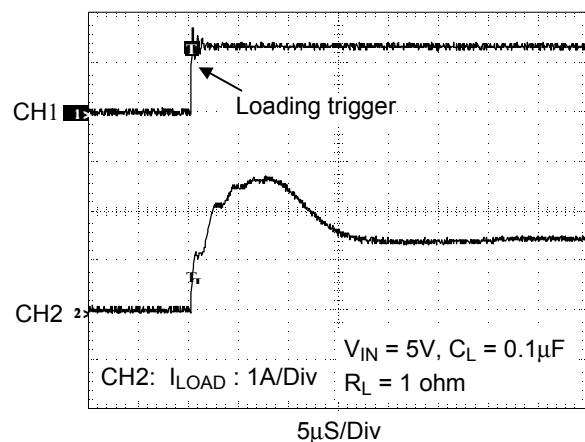


Current Limit vs. Voltage



Short Circuit Current vs. Temp.**Short Circuit Current vs. Voltage****CE Threshold vs. Temp.****CE Threshold vs. Voltage****Turn On Rising Time vs. Temp.****Turn Off Falling Time vs. Temp.**



UVLO at Rising**UVLO at Falling****Short Circuit Response****Thermal Shut Down Response****Ramped Load Response****Current Limit Response**

Functional Description

The RT9701 is a high-side single N-channel switch with active-high enable input.

Input and Output

VIN (input) is the power supply connection to the circuitry and the drain of the output MOSFET. VOUT (output) is the source of the output MOSFET. In a typical circuit, current flows through the switch from VIN to VOUT toward the load. Both VOUT pins must be short on the board and connected to the load and so do both VIN pins but connected to the power source.

Thermal Shutdown

Thermal shutdown shuts off the output MOSFET if the die temperature exceeds 130°C and 20°C of hysteresis forces the switch turning off until the die temperature drops to 110°C.

Soft Start

In order to eliminate the upstream voltage droop caused by the large inrush current during hot-plug events, the “soft-start” feature effectively isolates power supplies from such highly capacitive loads.

Undervoltage Lockout

UVLO prevents the MOSFET switch from turning on until input voltage exceeds 1.8V (typical). If input voltage drops below 1.8V (typical), UVLO shuts off the MOSFET switch.

Current Limiting and Short Protection

The current limit circuit is designed to protect the system supply, the MOSFET switch and the load from damage caused by excessive currents. The current limit threshold is set internally to allow a minimum of 1.1A through the MOSFET but limits the output current to approximately 1.5A typical. When the output is short to ground, it will limit to a constant current 0.5A until thermal shutdown or short condition removed.

Applications Information

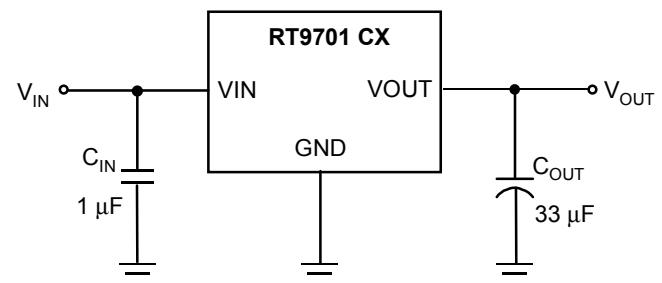


Fig. 1 High Side Power Switch

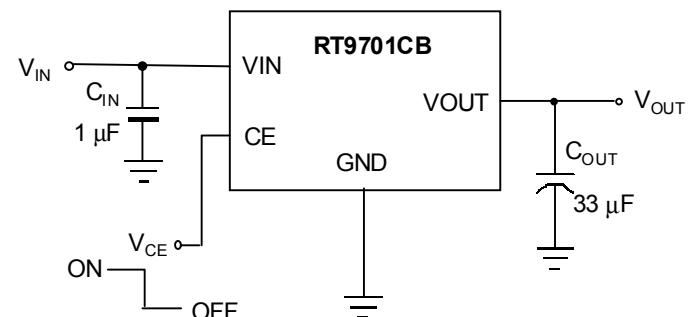


Fig. 2 High Side Power Switch with Chip Enable Control

Filtering

To limit the input voltage drop during hot-plug events, connect a 1μF ceramic capacitor from VIN to GND. However, higher capacitor values will further reduce the voltage drop at the input.

Connect a 33μF capacitor from VOUT to GND. This capacitor helps to prevent inductive parasitics from pulling VOUT negative during turn-off or EMI damage to other components during the hot-detachment. If RT9701 is implanted in device end application, minimum 1uF capacitor from VOUT to GND is recommended and higher capacitor values are also preferred.

In choosing these capacitors, special attention must be paid to the Effective Series Resistance, ESR, of the capacitors to minimize the IR drop across the capacitor's ESR.

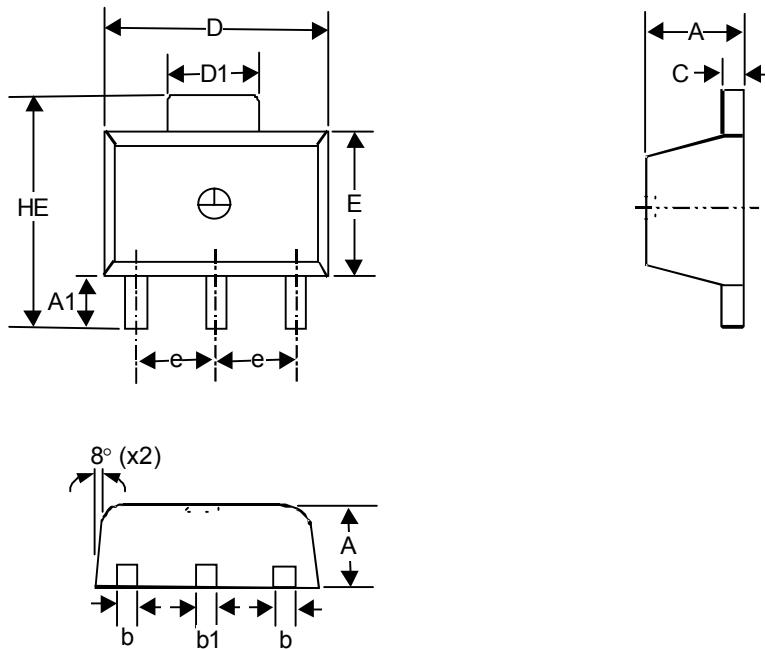
Ferrite beads in series with all power and ground lines are recommended to eliminate or significantly reduce EMI. In selecting a ferrite bead, the DC resistance of the wire used must be kept to a minimum to reduce the voltage drop.

Reverse current preventing

The output MOSFET and driver circuitry are also designed to allow the MOSFET source to be externally forced to a higher voltage than the drain ($V_{OUT} > V_{IN} \geq 0$). To prevent reverse current from such condition, disable the switch (RT9701CBL) or connect VIN to a fixed voltage under 1.3V.

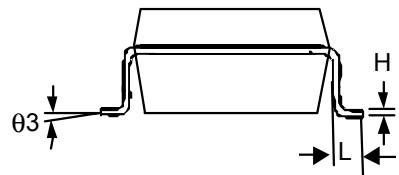
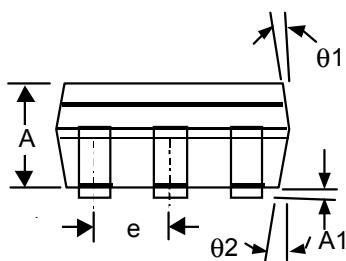
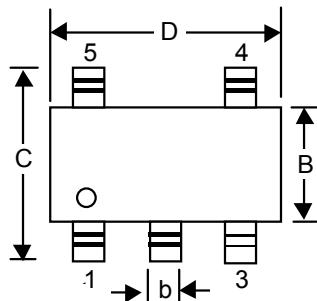
Layout and Thermal Dissipation

- Place the switch as close to the USB connector as possible. Keep all traces as short as possible to reduce the effect of undesirable parasitic inductance.
- Place the output capacitor and ferrite beads as close to the USB connector as possible.
- If ferrite beads are used, use wires with minimum resistance and large solder pads to minimize connection resistance.
- If the package is with dual VOUT or VIN pins, short both the same function pins to reduce the internal turn-on resistance.
- Under normal operating conditions, the package can dissipate the channel heat away. Wide power-bus planes connected to VIN and VOUT and a ground plane in contact with the device will help dissipate additional heat.

Package Information

Symbols	Dimensions In Millimeters			Dimensions In Inches		
	Min	Typ	Max	Min	Typ	Max
A	1.40	1.50	1.60	0.055	0.059	0.063
A1	0.90	1.00	1.10	0.035	0.039	0.043
b	0.36	0.42	0.48	0.014	0.016	0.018
b1	0.41	0.42	0.53	0.016	0.018	0.020
C	0.38	0.40	0.43	0.014	0.015	0.017
D	4.20	4.50	4.60	0.173	0.177	0.181
D1	1.40	1.60	1.75	0.055	0.062	0.069
HE	--	--	4.25	--	--	0.167
E	2.40	2.50	2.60	0.094	0.098	0.102
e	1.45	1.50	1.55	0.057	0.059	0.061

3-Lead SOT-89 Surface Mount



Symbols	Dimensions In Millimeters			Dimensions In Inches		
	Min	Typ	Max	Min	Typ	Max
A	1.000	1.100	1.300	0.039	0.043	0.051
A1	--	--	0.100	--	--	0.004
B	1.400	1.600	1.800	0.055	0.063	0.071
C	2.600	2.800	3.000	0.102	0.110	0.118
D	2.700	2.900	3.100	0.106	0.114	0.122
H	0.100	0.150	0.250	0.004	0.006	0.010
L	0.300	0.450	0.600	0.012	0.018	0.024
b	0.300	0.400	0.500	0.012	0.016	0.020
e	--	0.950	--	--	0.037	--
θ1	2°	--	8°	--	--	--
θ2	5°	--	10°	--	--	--
θ3	--	--	10°	--	--	--

5-Lead SOT- 25 Surface Mount Package

RichTek Technology Corp.
6F, No. 35, Hsintai Road, Chupei City
Hsinchu, Taiwan, R.O.C.
Tel: (8863)5510047 Fax: (8863)5537749

Taipei Office (Marketing)
4F-1, No. 127, Lane 235, Paochiao Road, Hsintien City
Taipei County, Taipei, R.O.C.
Tel: (8862)89191466 Fax: (8862)89191465
Email: marketing@richtek-ic.com.tw